

Characterization of Crystal Structure and Morphology of Ultra-Thin 2D MoS2 Layers Using X-ray Metrology

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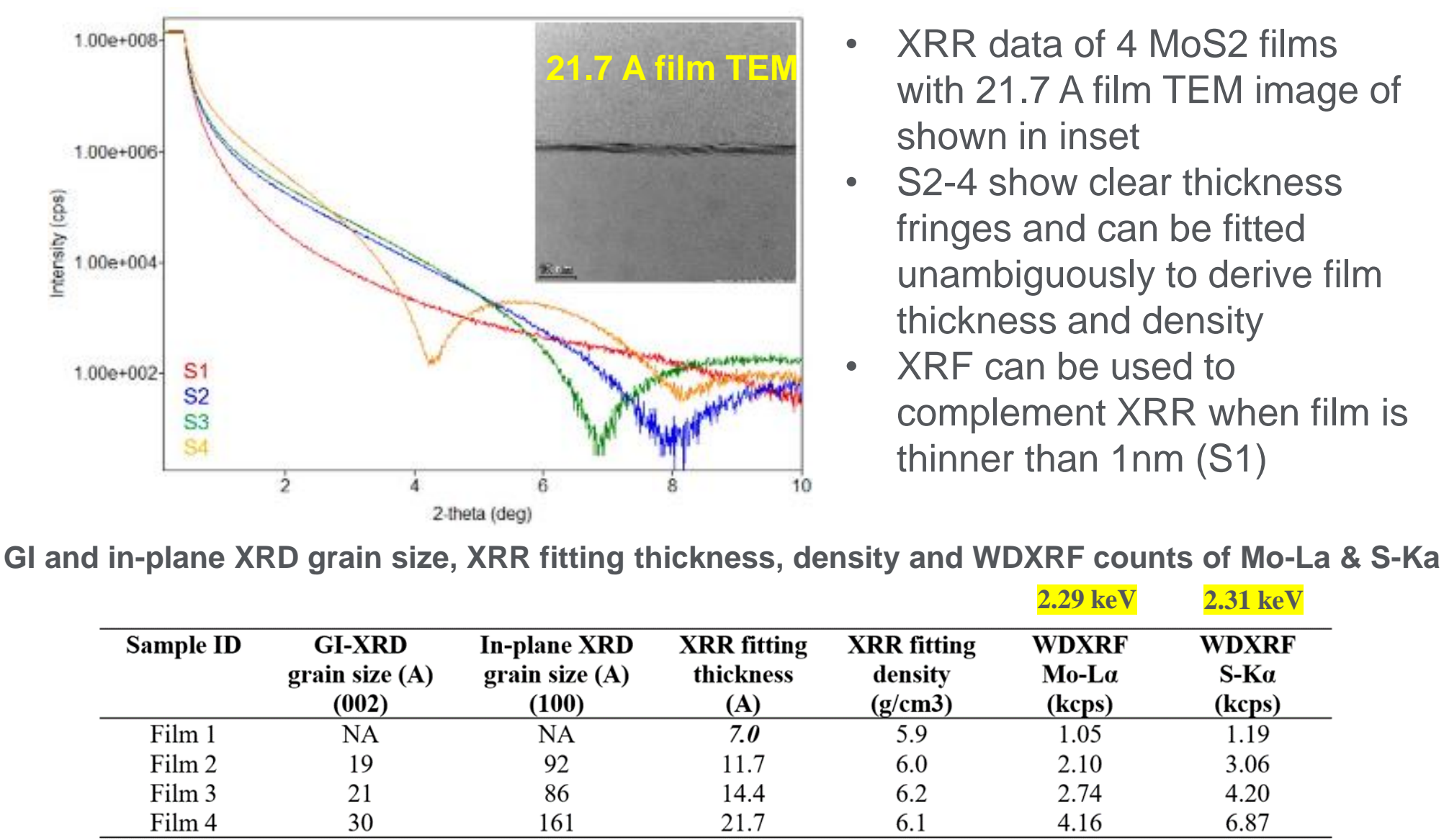
Introduction

- Few-layered two-dimensional transition metal dichalcogenides (2D TMDs) are strong candidates for several applications such as high mobility channel in memory or logic devices, photovoltaics, photodetectors, and optoelectronics
- Since high-quality ultra-thin layers are needed to take full advantage of these 2D materials, precise control of the crystallinity, morphology and thickness of these ultra-thin layers is critical. This requires a set of metrology techniques highly sensitive to these ultra-thin layers and fast enough to provide rapid feedback to help optimize deposition parameters

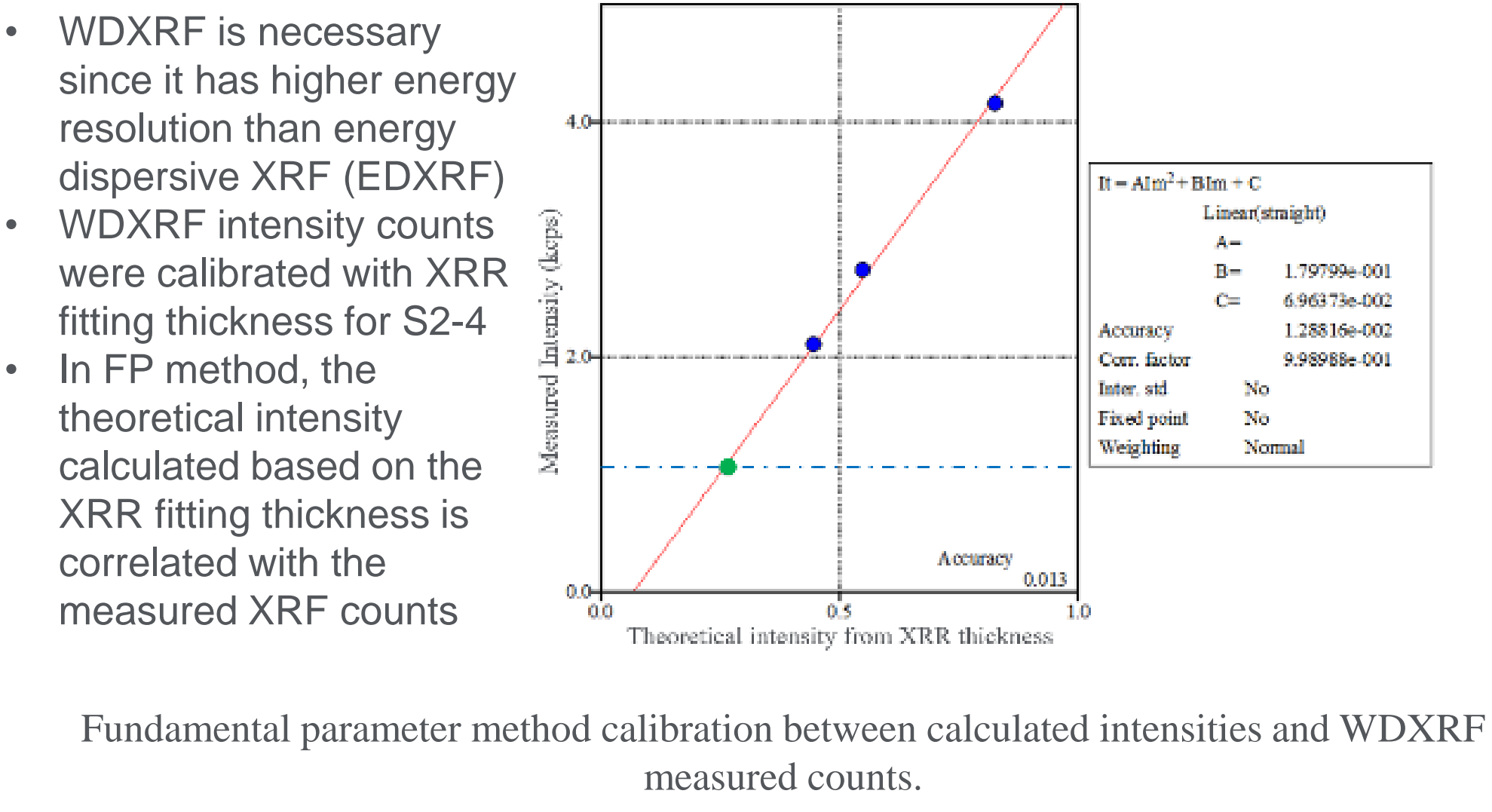
AMAT Solution

- We use a combination of X-ray scattering and fluorescence metrology techniques, including grazing incidence X-ray diffraction (GI-XRD), in-plane X-ray diffraction (In-plane XRD), X-ray reflectivity (XRR) and wavelength dispersive X-ray fluorescence (WDXRF) to characterize MoS2 samples of various thicknesses
- We show that this fast and non-destructive X-ray based metrology is sensitive to crystal phase, crystallite grain size, thickness, density, composition, and uniformity of the MoS2 films down to sub-nm thickness

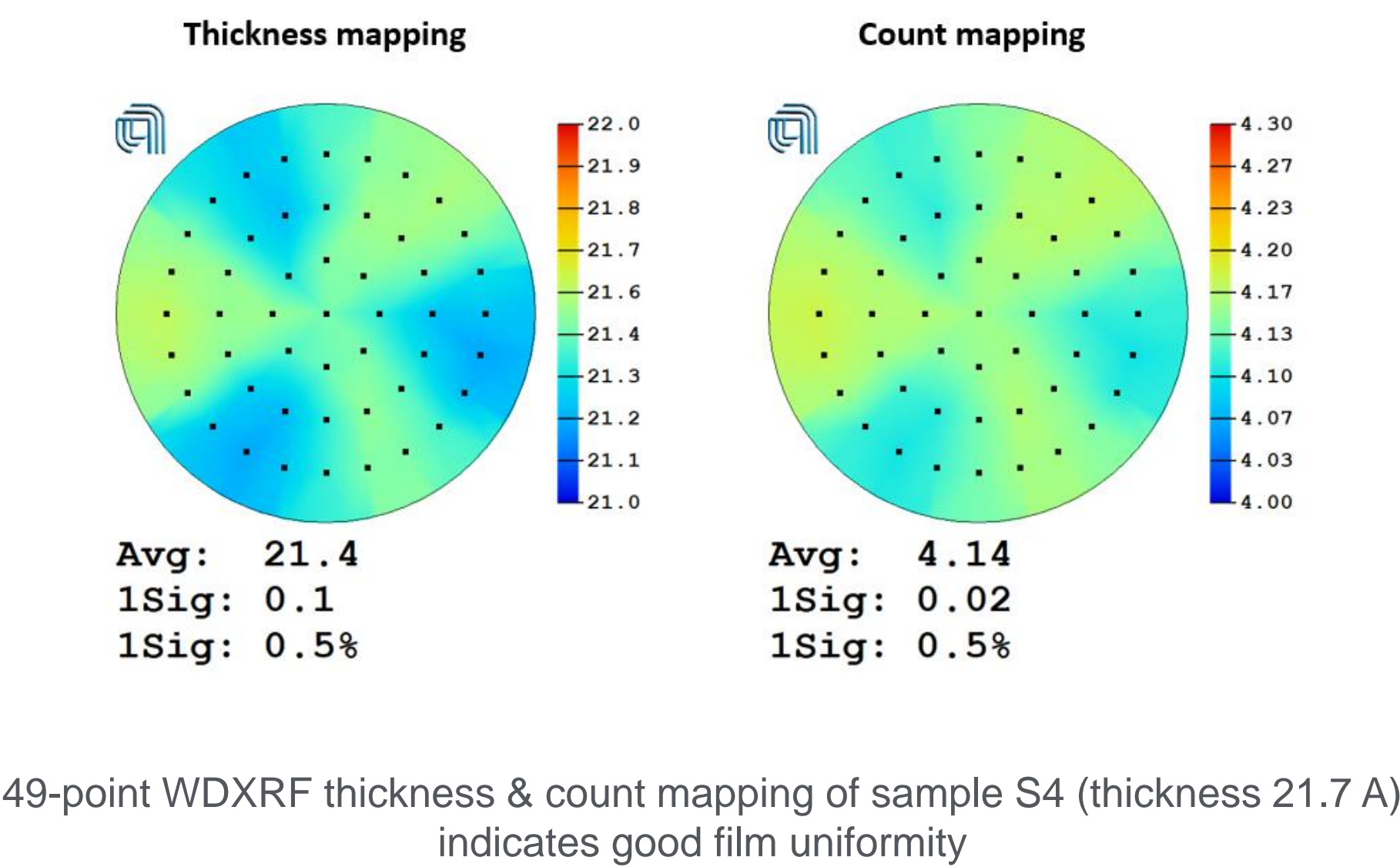
XRR Data of MoS2



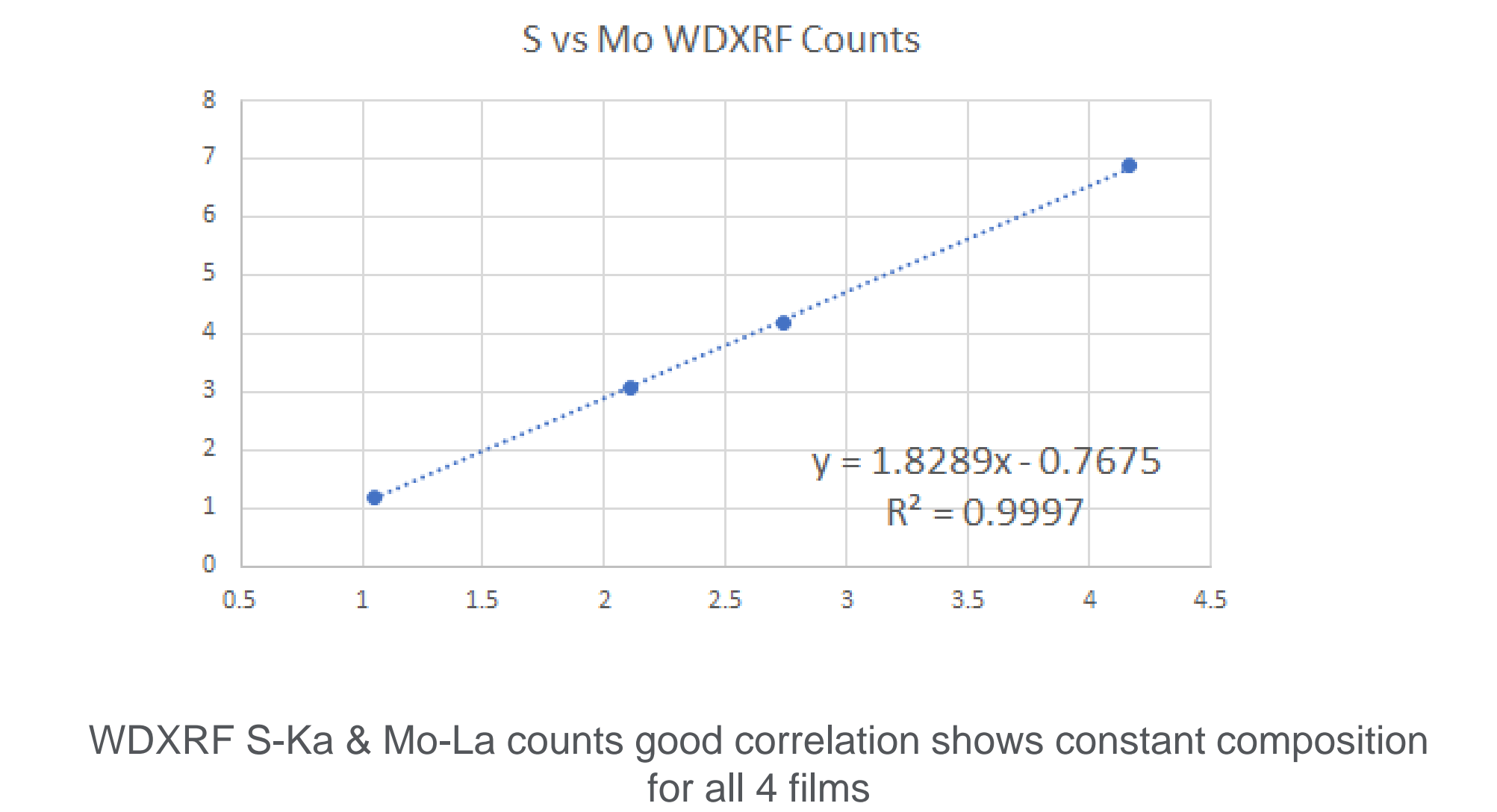
WDXRF FP Method Calibration



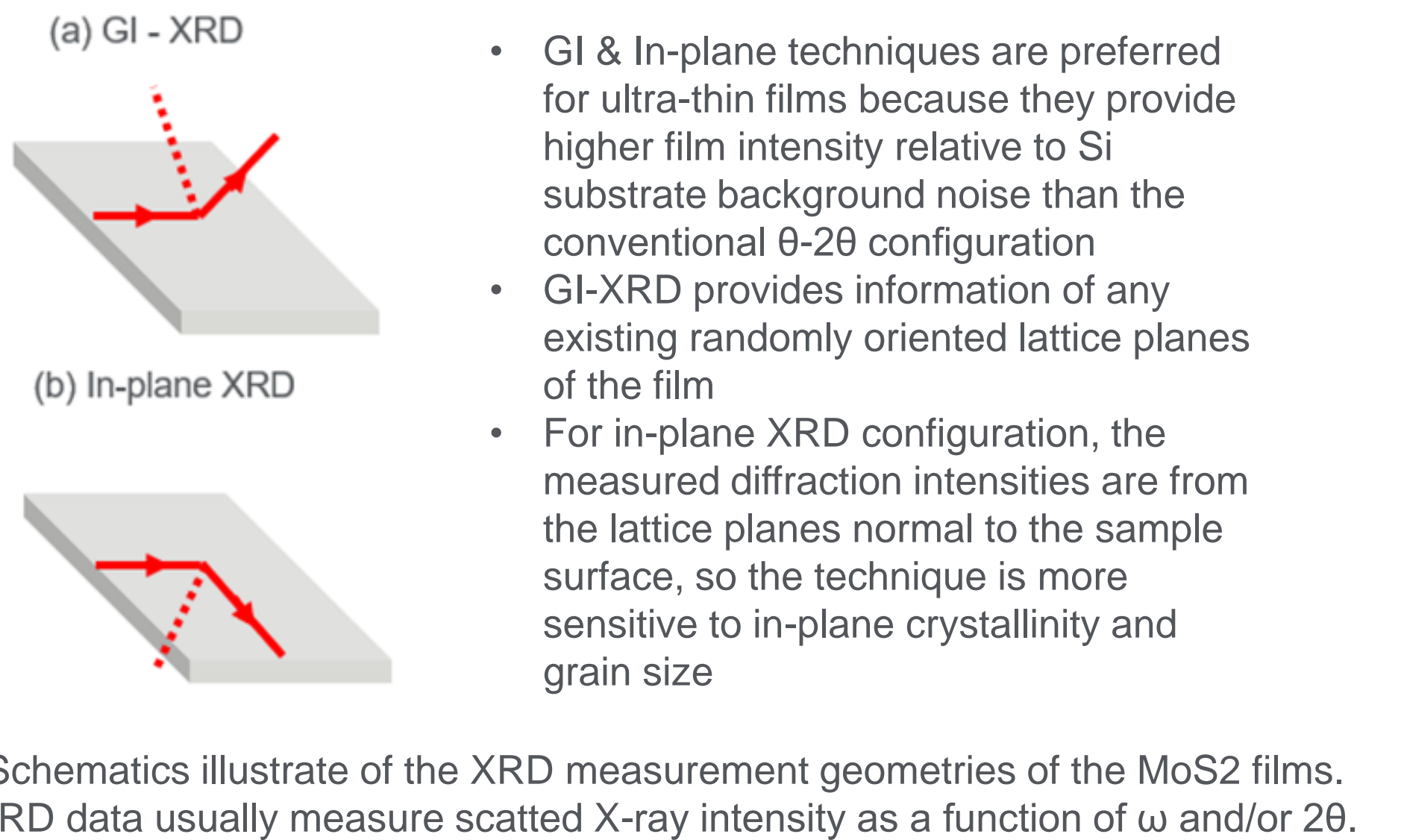
WDXRF Mapping & Uniformity Data



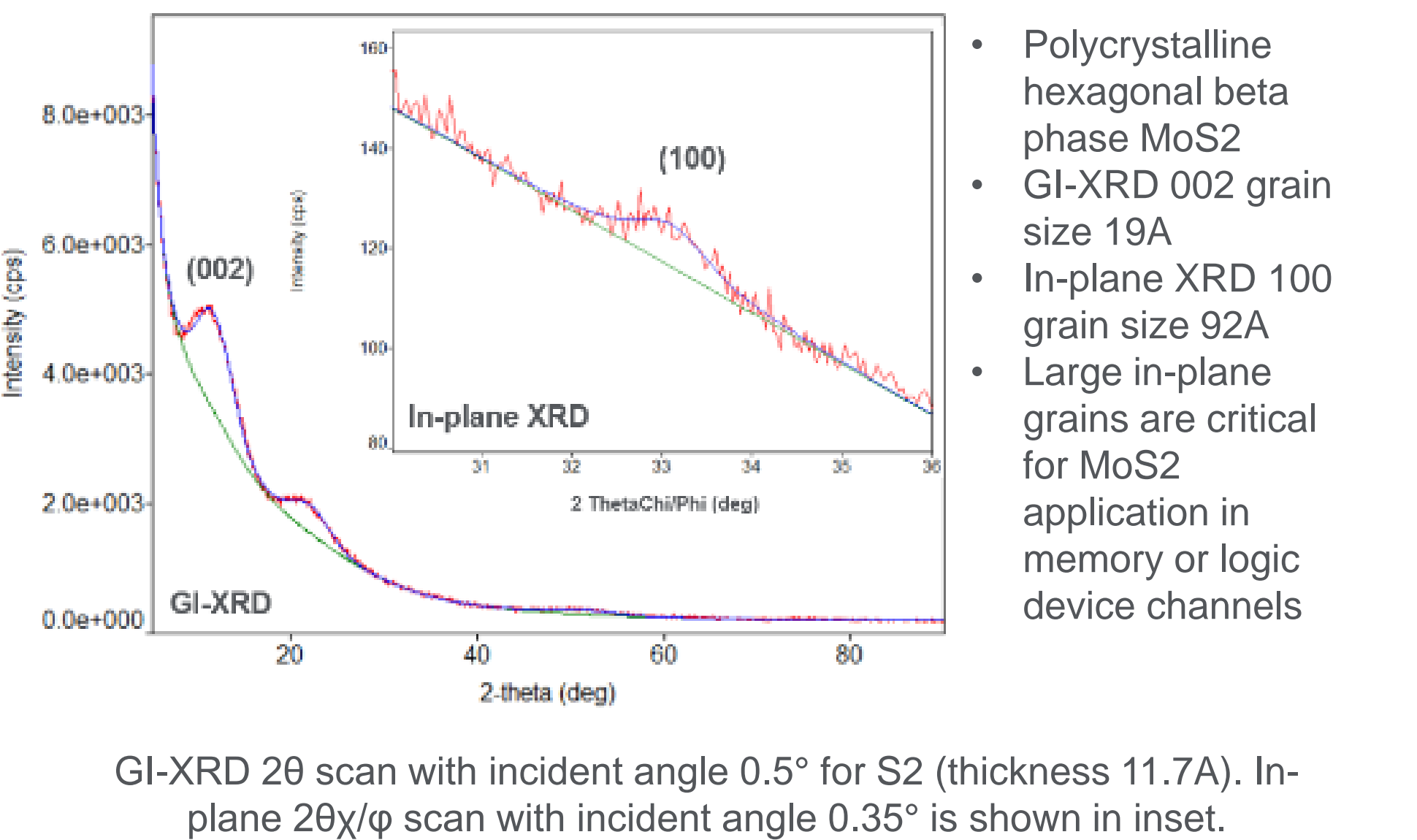
WDXRF Consistent Composition Data



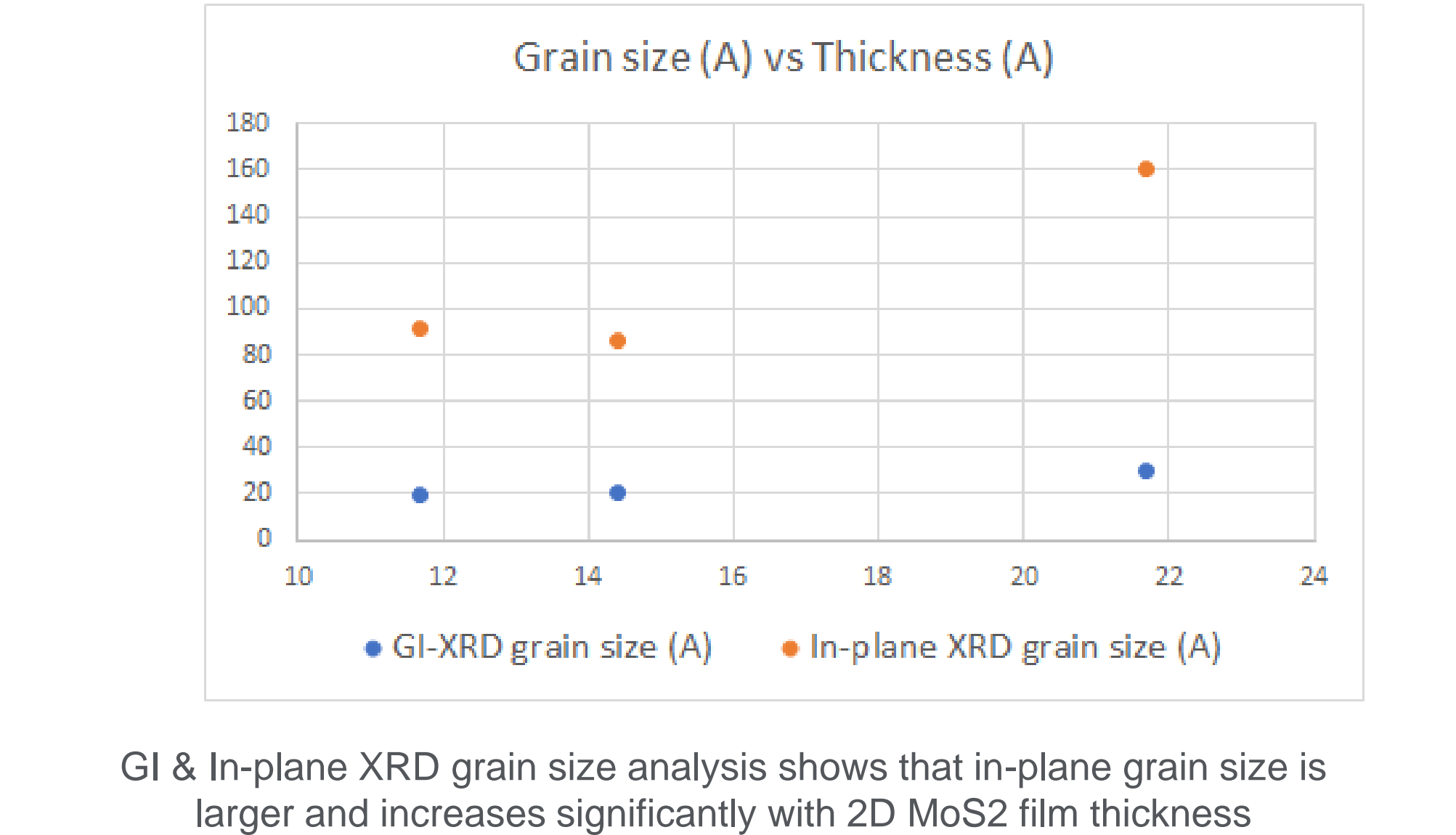
XRD Configuration of Thin Film



XRD Data of MoS2



XRD Grain Size & Thickness of MoS2



Conclusion

- XRR combined with WDXRF are suitable for characterization of 2D MoS2 films in a wider range of thicknesses
- In-plane XRD is sensitive to MoS2 lateral grain size which is a key performance driver for 2D MoS2 based devices
- This suite of X-ray based metrology techniques offers a fast, non-destructive, and sensitive methodology for in-depth characterization and optimization of ultra-thin layer 2D materials